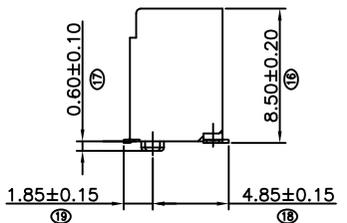
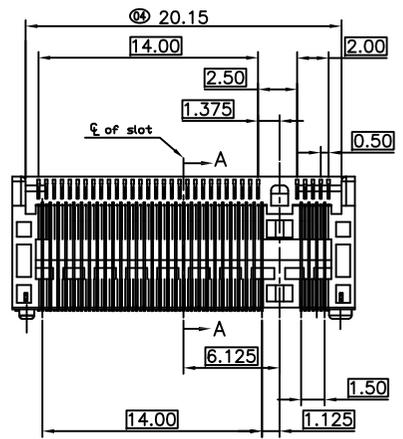
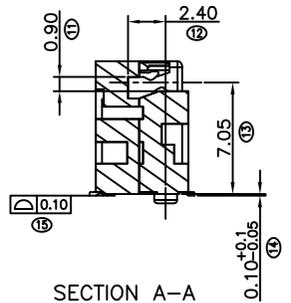
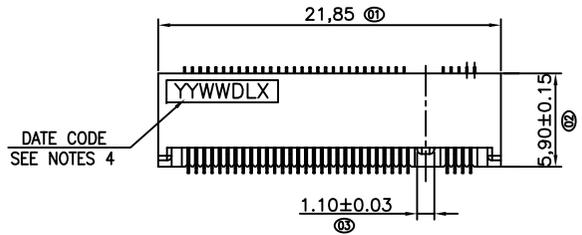


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/06/13	Ken Lin



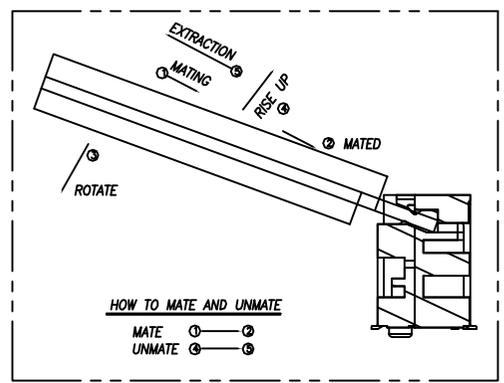
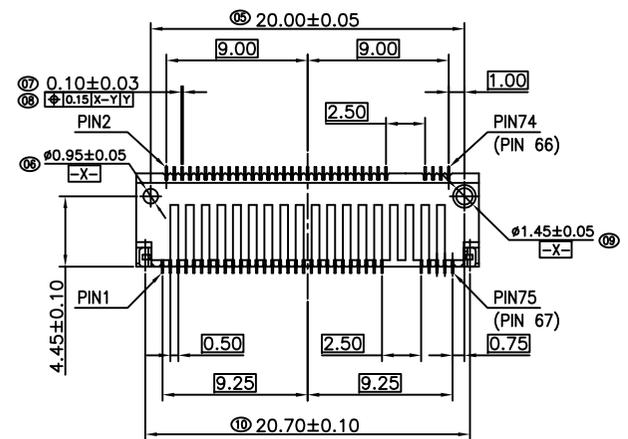
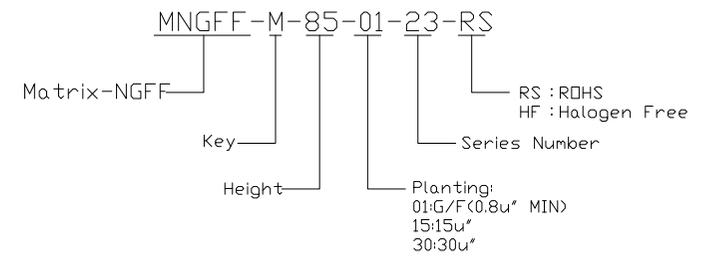
- NOTES:
- MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, COLOR: BLACK
 - CONTACTS: COPPER ALLOY
 - PEG: STAINLESS STEEL.
 - REFLOW SOLDER CAPABLE TO 260°C
 - FINISH:

CONTACT:

GOLD FLASH (0.5u" MIN.) PLATED ON CONTACT AREA AND SOLDER AREA.
 50u" MIN. NICKEL UNDERPLATING OVERALL.
 PEG: 80u" MIN. MATTE-TIN PLATED ON SOLDERING AREA.
 50u" MIN. NICKEL UNDERPLATING.
 - DATE CODE: YYMMWDLX

YY: YEAR (09: 2009)
 WW: WEEK (25: THE 25TH WEEK)
 D: DAY (1~7: SUNDAY~SATURDAY)
 L: LINE NUMBER OF ASSEMBLY (A: LINE A)
 X: D OR N (D: DAY, N: NIGHT)
 - CONNECTOR ACTUAL PIN QUANTITY IS 67, AS THE KEY TAKING OUT 8 PINS.
 - MATERIALS HALOGEN FREE & RoHS COMPLIANT.

ORDER INFORMATION :



Matrix Electronics Co., Ltd			
TOLERANCE: X:X ±0.50 X:XX ±0.38 X:XXX ±0.25 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2022/06/13	PART NAME: NGFF Socket (M2 Connector) H8.50, M Key
	CHECKED BY: Vicky Hsieh	DATE : 2022/06/13	PART NO. MNGFF-M-85-01-23-RS
	APPROVED BY1: Richard Hsieh	DATE : 2022/06/13	MOLD NO. NA
UNIT: mm [inch]	APPROVED BY2: Richard Hsieh	DATE : 2022/06/13	DRAW NO.
SCALE: 1:1	SIZE: A4		SHEET NO. 1 OF 2

